

N-Channel 20 V (D-S) MOSFET

PRODUCT SUMMARY					
V _{DS} (V)	$R_{DS(on)}\left(\Omega\right)$ Max.	I _D (A)	Q _g (Typ.)		
20	$0.420 \text{ at V}_{GS} = 4.5 \text{ V}$	0.5			
	$0.492 \text{ at V}_{GS} = 2.5 \text{ V}$	0.2	1 nC		
	0.597 at V _{GS} = 1.8 V	0.2	TIIC		
	0.762 at V _{GS} = 1.5 V	0.05			

FEATURES

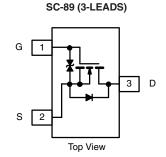
- TrenchFET® Power MOSFET
- Gate-Source ESD Protected: 1000 V
- Material categorization: For definitions of compliance please see www.vishay.com/doc?99912

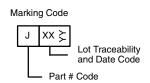


HALOGEN FREE

APPLICATIONS

- Load/Power Switching for Portable Devices
- Drivers: Relays, Solenoids, Lamps, Hammers, Displays, Memories
- **Battery Operated Systems**
- **Power Supply Converter Circuits**





Ordering Information: Si1062X-T1-GE3 (Lead (Pb)-free and Halogen-free)

ABSOLUTE MAXIMUM RATINGS (T _A = 25 °C, unless otherwise noted)						
Parameter	Symbol	Limit	Unit			
Drain-Source Voltage		V _{DS}	20	V		
Gate-Source Voltage		V_{GS}	± 8	ľ		
Continuous Drain Current (T _{.I} = 150 °C) ^a	T _A = 25 °C	I_	0.53 ^{a, b}			
Continuous Diam Current (1) = 150°C)	T _A = 70 °C	- I _D	0.43 ^{a, b}	Α		
Pulsed Drain Current (t = 300 μs)		I _{DM}	2]		
Continuous Source-Drain Diode Current	T _A = 25 °C	I _S	0.18 ^{a, b}	Α		
Marianum Daviau Dinainational	T _A = 25 °C	P _D	0.22 ^{a, b}	W		
Maximum Power Dissipation ^a	T _A = 70 °C	ט י	0.14 ^{a, b}] "		
Operating Junction and Storage Temperature Range		T _J , T _{stg}	- 55 to 150	°C		

THERMAL RESISTANCE RATINGS						
Parameter	Symbol	Тур.	Max.	Unit		
Marrian In a stinut to Ameleian to	t ≤ 5 s	R _{thJA}	440	530	°C/W	
Maximum Junction-to-Ambient ^D	Steady State	' 'thJA	540	650		

Notes:

a. Surface mounted on 1" x 1" FR4 board.

b. t = 5 s.

Si1062X

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SPECIFICATIONS (T _J = 25 °C, unless otherwise noted)							
Parameter	Symbol	Test Conditions	Min.	Тур.	Max.	Unit	
Static						•	
Drain-Source Breakdown Voltage	V_{DS}	$V_{GS} = 0 \text{ V}, I_D = 250 \mu\text{A}$	20			V	
V _{DS} Temperature Coefficient	$\Delta V_{DS}/T_{J}$	I _D = 250 μA		11		mV/°C	
V _{GS(th)} Temperature Coefficient	$\Delta V_{GS(th)}/T_J$	I _D = 250 μA		- 1.8			
Gate-Source Threshold Voltage	V _{GS(th)}	$V_{DS} = V_{GS}, I_D = 250 \mu A$	0.4		1	V	
Gate-Source Leakage	1	$V_{DS} = 0 \text{ V}, V_{GS} = \pm 8 \text{ V}$			± 30		
	l _{GSS}	$V_{DS} = 0 \text{ V}, V_{GS} = \pm 4.5 \text{ V}$			± 1	μΑ	
Zara Cata Valtaga Drain Current	1	V _{DS} = 20 V, V _{GS} = 0 V			1		
Zero Gate Voltage Drain Current	I _{DSS}	$V_{DS} = 20 \text{ V}, V_{GS} = 0 \text{ V}, T_{J} = 85 ^{\circ}\text{C}$			10		
On-State Drain Current ^a	I _{D(on)}	$V_{DS} = \ge 5 \text{ V}, V_{GS} = 4.5 \text{ V}$	2			Α	
		$V_{GS} = 4.5 \text{ V}, I_D = 0.5 \text{ A}$		0.350	0.420		
Drain-Source On-State Resistance ^a	Б	$V_{GS} = 2.5 \text{ V}, I_D = 0.2 \text{ A}$		0.410	0.492		
Drain-Source On-State Resistance	R _{DS(on)}	$V_{GS} = 1.8 \text{ V}, I_D = 0.2 \text{ A}$		0.459	0.597	Ω	
		$V_{GS} = 1.5 \text{ V}, I_D = 0.05 \text{ A}$		0.510	0.762		
Forward Transconductance	9 _{fs}	V _{DS} = 10 V, I _D = 0.5 A		7.5		S	
Dynamic ^b						1	
Input Capacitance	C _{iss}			43		pF	
Output Capacitance	C _{oss}	$V_{DS} = 10 \text{ V}, V_{GS} = 0 \text{ V}, f = 1 \text{ MHz}$		14			
Reverse Transfer Capacitance	C _{rss}			8			
Total Cata Charga	Q _g	$V_{DS} = 10 \text{ V}, V_{GS} = 8 \text{ V}, I_D = 0.5 \text{ A}$		1.8	2.7		
Total Gate Charge				1	2	nC	
Gate-Source Charge		$V_{DS} = 10 \text{ V}, V_{GS} = 4.5 \text{ V}, I_{D} = 0.5 \text{ A}$		0.16			
Gate-Drain Charge	Q_{gd}			0.13			
Gate Resistance	R_{g}	f = 1 MHz		12.2		Ω	
Turn-On Delay Time	t _{d(on)}			2	4		
Rise Time	t _r	V_{DD} = 10 V, R_L = 20 Ω		14	24	ns	
Turn-Off Delay Time	t _{d(off)}	$I_D \cong 0.4 \text{ A}, V_{GEN} = 4.5 \text{ V}, R_g = 1 \Omega$		16	30		
Fall Time	t _f			11	20		
Drain-Source Body Diode Characterist	ics		<u>'</u>				
Pulse Diode Forward Current ^a	I _{SM}				2	Α	
Body Diode Voltage	V _{SD}	I _S = 0.4 A		0.8	1.2	V	
Body Diode Reverse Recovery Time	t _{rr}			10	15	ns	
Body Diode Reverse Recovery Charge	Q _{rr}	Q _{rr}		2	4	nC	
Reverse Recovery Fall Time	t _a	I _F = 0.4 A, dI/dt = 100 A/μs		5		ns	
Reverse Recovery Rise Time	t _b			5			

Notes:

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

a. Pulse test; pulse width $\leq 300~\mu s,$ duty cycle $\leq 2~\%.$

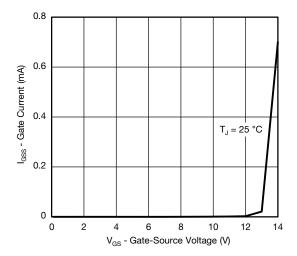
b. Guaranteed by design, not subject to production testing.

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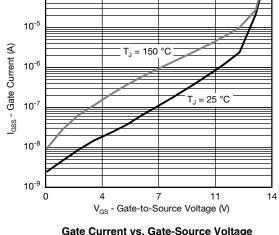


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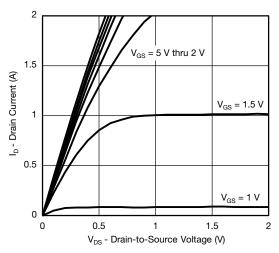
TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)



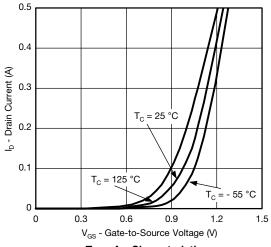
Gate Current vs. Gate-Source Voltage



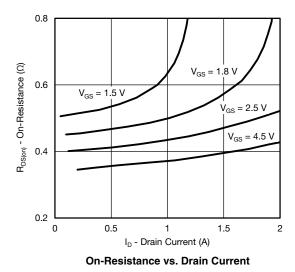
Gate Current vs. Gate-Source Voltage

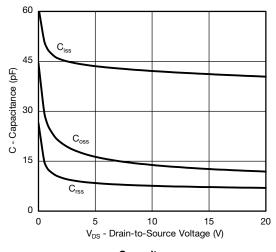


Output Characteristics



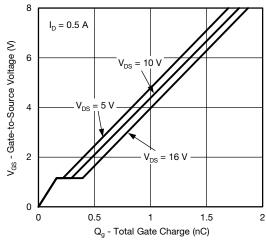
Transfer Characteristics



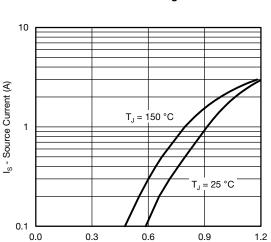


Capacitance

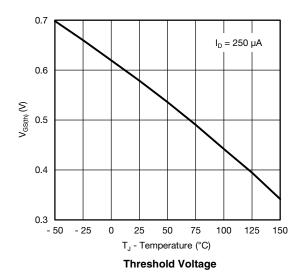
TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)

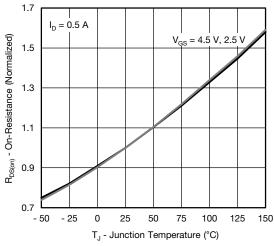


Gate Charge

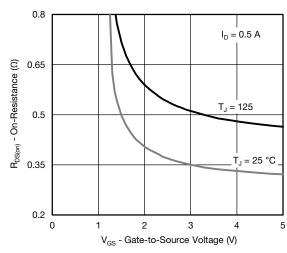


 V_{SD} - Source-to-Drain Voltage (V) Soure-Drain Diode Forward Voltage

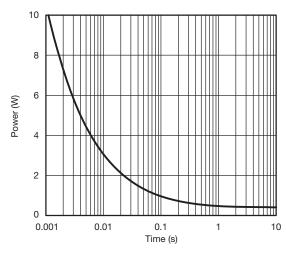




On-Resistance vs. Junction Temperature



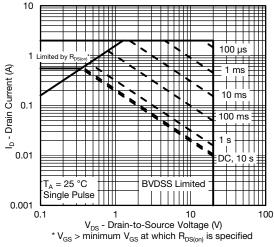
On-Resistance vs. Gate-to-Source Voltage



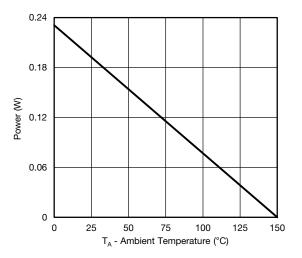
Single Pulse Power, Junction-to-Ambient



TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)

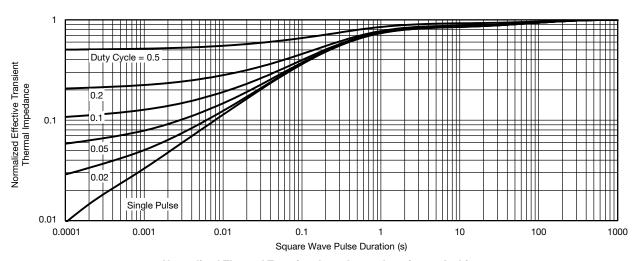






Power Derating, Junction-to-Ambient

 $^{^*}$ The power dissipation P_D is based on $T_{J(max)}$ = 150 $^{\circ}$ C, using junction-to-case thermal resistance, and is more useful in settling the upper dissipation limit for cases where additional heatsinking is used. It is used to determine the current rating, when this rating falls below the package limit.



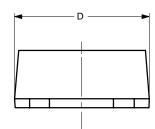
Normalized Thermal Transient Impedance, Junction-to-Ambient

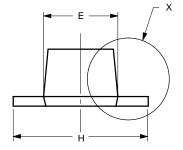
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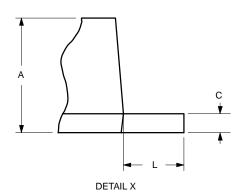


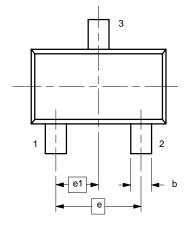


SC89-3





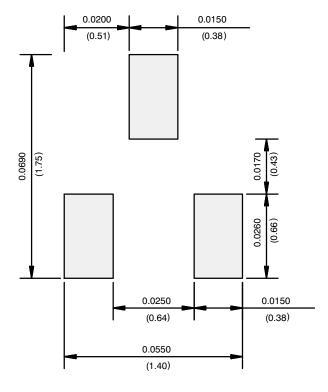




	MILLIM	IETERS	INCHES		
Dim	Min	Max	Min	Max	
Α	0.60	0.80	0.024	0.031	
b	0.23	0.33	0.009	0.013	
С	0.10	0.20	0.004	0.008	
D	1.50	1.70	0.059	0.067	
Е	0.75	0.95	0.030	0.037	
е	1.00 BSC		0.040 BSC		
e ₁	0.50 BSC		0.020	BSC	
Н	1.50	1.70	0.059	0.067	
L	0.30	0.50	0.012	0.020	



RECOMMENDED MINIMUM PADS FOR SC-89: 3-Lead



Recommended Minimum Pads Dimensions in Inches/(mm)

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